



IPC-7092

# **Design and Assembly Process Implementation for Embedded Components**

Developed by the Embedded Devices Process Implementation Subcommittee (D-55) of the Embedded Components Committee (D-50) of IPC

Users of this publication are encouraged to participate in the development of future revisions.

Contact:

IPC  
3000 Lakeside Drive, Suite 309S  
Bannockburn, Illinois  
60015-1249  
Tel 847 615.7100  
Fax 847 615.7105

# Table of Contents

<b>1 SCOPE</b> .....	1	3.1.28 Printed Circuit .....	6
1.1 Purpose .....	1	3.1.29 Printed Circuit Board .....	6
1.2 Intent .....	1	3.1.30 Production Board .....	6
<b>2 APPLICABLE DOCUMENTS</b> .....	1	3.1.31 Production Panel (PP) .....	6
2.1 IPC .....	1	3.1.32 Production Printed Board (PPB) .....	6
2.2 Joint Industry Standards .....	2	3.1.33 Stacked Via/Microvia .....	6
2.3 ASME .....	2	3.1.34 Temperature Delta ( $\Delta T$ )* .....	6
2.4 GEIA .....	2	3.1.35 Temperature Coefficient of Capacitance* .....	6
2.5 JEDEC .....	2	3.1.36 Temperature Coefficient of Resistance* .....	6
2.6 IEC .....	2	3.1.37 Thermal Expansion Mismatch .....	6
2.7 ISO/IEC .....	2	3.1.38 Thermal Resistance .....	6
<b>3 GENERAL DESCRIPTION</b> .....	3	3.2 Technology Overview .....	6
3.1 Terms and Definitions .....	4	3.2.1 Passive (Resistors, Capacitors, Inductors, etc.) .....	8
3.1.1 Active Device .....	4	3.2.2 Active (Transistors, Memory, Semiconductors, etc.) .....	9
3.1.2 Active Trimming .....	4	3.3 Embedded (Placed) Technology .....	10
3.1.3 Capacitance* .....	4	3.3.1 Passive (Resistors, Capacitors, Inductors, etc.) .....	10
3.1.4 Coefficient of Thermal Expansion .....	4	3.3.2 Active (Transistors, Memory, Semiconductors, etc.) .....	10
3.1.5 Device .....	4	3.4 Material Requirements .....	11
3.1.6 Discrete Component* .....	4	3.4.1 Mounting Materials .....	11
3.1.7 Embedded Active Component (Device) .....	4	3.4.2 Component Formation Materials .....	12
3.1.8 Embedded Component .....	4	3.4.3 Attachment Materials .....	12
3.1.9 Embedded Component (Placed) .....	4	3.4.4 Encapsulation Materials .....	12
3.1.10 Embedded Component (Formed) .....	4	3.5 Cost Analysis .....	12
3.1.11 Embedded Component Base-Core (ECBC)* .....	4	3.5.1 Fabrication and Manufacturing Cost Modeling .....	13
3.1.12 Embedded Component Board Assembly (ECBA)* .....	4	3.5.2 Life Cycle Costs Impacted by Embedded Components .....	14
3.1.13 Embedded Component Printed Board (ECPB)* .....	4	3.6 Product Safety Design Considerations .....	15
3.1.14 Embedded Component Substrate* .....	4	3.7 Case Study and Decision Making .....	15
3.1.15 Embedded Substrate Mounting* .....	4	3.7.1 General Case Study .....	16
3.1.16 Embedded Passive .....	4	3.7.2 Scenarios for Embedded Components .....	16
3.1.17 Embedded Passive Component (Device) .....	5	<b>4 COMPONENT CONSIDERATIONS</b> .....	16
3.1.18 Embedded Substrate Board* .....	5	4.1 General Requirements .....	16
3.1.19 Face Down Bonding* .....	5	4.1.1 Part Robustness Evaluations .....	16
3.1.20 Face Up Bonding* .....	5	4.1.2 Test Method Correlation .....	17
3.1.21 Integrated Passive Component .....	5	4.1.3 Determining Values That Can Be Placed .....	17
3.1.22 Mounting Base* .....	5	4.2 Component Preparation .....	17
3.1.23 Multilayer Printed Board (nonpreferred term, “multilayer printed circuit board”)* .....	5	4.2.1 Passive Component Issues .....	17
3.1.24 Passive Array (Embedded)* .....	5	4.2.2 Semiconductor Die Issues .....	17
3.1.25 Passive Component (Element) .....	5	4.2.3 Surface Redistribution .....	17
3.1.26 Passive Network (Embedded)* .....	6		
3.1.27 Printed Board (PB) .....	6		

4.3	Post Process Validations .....	18	<b>7</b>	<b>MOUNTING BASE OR BOARD STACKUP CONSIDERATIONS</b> .....	44
4.4	Known Good Die (KGD) .....	18	7.1	Mounting Base .....	44
<b>5</b>	<b>MATERIALS</b> .....	19	7.2	Surface Finish for Placed Components .....	44
5.1	Organic Resins .....	19	7.2.1	Electroless Nickel/Immersion Gold (ENIG) .....	44
5.1.1	Multilayer PCB Stack-Up Design .....	20	7.2.2	Electroless Nickel/Electroless Palladium/ Immersion Gold (ENEPIG) .....	45
5.1.2	Selecting Relative Dielectric Constant .....	20	7.2.3	Organic Solderability Preservative (OSP) .....	45
5.2	Nonorganic Products .....	20	7.2.4	Electrolytic Nickel/Electrolytic Gold .....	45
5.3	Conductor Characteristics (Copper Foil/Film) .....	20	7.2.5	Direct Immersion Gold (DIG) .....	45
5.4	Component Forming Material .....	21	7.2.6	Immersion Silver .....	45
5.4.1	Embedded Passive Component Selection Criteria .....	21	7.2.7	Immersion Tin .....	45
5.4.2	Formed Resistors .....	21	7.2.8	Copper .....	45
5.4.3	Thick Film Resistor Cost and Performance .....	22	7.3	Capacitor Component Formation Process .....	45
5.4.4	Sheet Film Type Resistor Elements .....	28	7.3.1	Planar Capacitance .....	45
5.4.5	Embedded Capacitors .....	31	7.3.2	Plane Layer Separation .....	46
5.4.6	Formed Inductors .....	34	7.3.3	Discrete Formed Capacitor Element .....	46
5.4.7	Formed Active Components .....	37	7.4	Component Attachment Process .....	46
5.5	Adhesives (Conductive/Nonconductive) .....	37	7.5	Dielectric Encapsulation .....	47
5.5.1	Polymer Adhesives .....	38	7.5.1	Reinforced Prepreg .....	48
5.5.2	Dry-Film Adhesives .....	38	7.5.2	Unreinforced Resin .....	49
5.6	Solder and Other Attachment Materials .....	38	7.5.3	Resin-Coated Copper (RCC) .....	50
5.7	Plating Material Properties (Characteristics, Application For Attachment) .....	39	7.6	Via Hole Preparation and Interconnectivity .....	50
5.7.1	Electrode Finish Compatibility .....	39	7.7	Additional Layers and Hole Preparation .....	51
<b>6</b>	<b>EMBEDDED COMPONENT PROCESS CHARACTERISTICS</b> .....	39	7.8	Embedded Structure Descriptions .....	55
6.1	Forming Passive Components .....	39	7.8.1	Embedded Structure Type A .....	56
6.1.1	Tolerance Capability Evaluations .....	39	7.8.2	Embedded Structure Type B .....	60
6.2	Forming Active Components .....	40	7.8.3	Embedded Structure Type C .....	63
6.3	Placing Passive Components .....	40	7.8.4	Embedded Structure Type D .....	67
6.3.1	Shape Configuration .....	40	7.8.5	Embedded Structure Type E .....	71
6.3.2	Electrode Metallization .....	41	7.8.6	Processes Parameters for Structure Type F1, Embedded Core Technology .....	74
6.3.3	Shape and Configuration Considerations for Embedding .....	41	<b>8</b>	<b>DESIGN METHODOLOGY</b> .....	77
6.3.4	Electrode Susceptibility .....	41	8.1	Total Circuit Consideration .....	77
6.3.5	Component Encapsulation .....	41	8.1.1	Internal Component Mounting .....	80
6.4	Placing Active Components .....	41	8.1.2	External Component Mounting .....	80
6.4.1	Attachment Techniques .....	42	8.1.3	Circuit Interfaces .....	81
6.4.2	Face-Down Attachment .....	42	8.1.4	Internal Discrete Heat Sink .....	81
6.4.3	Gold-to-Gold Interface (GGI) .....	42	8.2	Layout Strategy .....	81
6.4.4	Face-Up Microvia Interface .....	42	8.2.1	Product Functional Description .....	82
6.4.5	Protective Die Methods .....	43	8.2.2	Engineering Actions .....	83
6.5	Consideration for Combining Processes .....	43	8.2.3	Design Density Analysis .....	86
6.5.1	Mixed Component Types .....	44	8.2.4	Candidate for Embedding .....	86
6.5.2	Placement and Forming Combinations .....	44	8.2.5	Circuitry to be Embedded .....	89
			8.3	PCB Layer Construction and Geometries .....	91
			8.3.1	Using Radius Bends and Blind/Buried Vias .....	91



Figure 5-11	Laser Trim Examples .....	26	Figure 7-7	Printed Board Fabrication and Assembly Terminology – Design to Finished Product .....	53
Figure 5-12	Traditional ECPB Lamination Process Sequence .....	27	Figure 7-8	Design Layout Steps Prior to Embedded Component Board Assembly Density Feasibility .....	54
Figure 5-13	Reverse ECPB Lamination Process Sequence .....	27	Figure 7-9	A1 Base-Core Example With Placed Passive Components on One Side .....	57
Figure 5-14	Thin-Film Resistor Forming Process .....	28	Figure 7-10	A1 Process Flow .....	57
Figure 5-15	Series Coupled Resistor Configuration with a Uniform Cu and R Element Width .....	29	Figure 7-11	A2 Base-Core Example with Placed Active Components on One Side .....	58
Figure 5-16	Maximize Isolation of Resistor Element to Minimize Physical Stress Damage Potential During Drill Operations .....	29	Figure 7-12	A2 Process Flow .....	58
Figure 5-17	Resistor Length Defined .....	30	Figure 7-13	A3 Base-Core Example With Placed Passive And Active Components on One Side .....	59
Figure 5-18	Resistor Width Defined .....	30	Figure 7-14	A3 Process Flow .....	59
Figure 5-19	Resistor in Ground Plane Example .....	31	Figure 7-15	B1 Base-Core Example With Placed Passive Components on Both Sides .....	60
Figure 5-20	Planar Capacitor Example .....	31	Figure 7-16	B1 Process Flow .....	60
Figure 5-21	Power and Ground Plane Interface .....	32	Figure 7-17	B2 Base-Core Example with Placed Active Components on Both Sides .....	61
Figure 5-22	Divided Planar Capacitor .....	33	Figure 7-18	B2 Process Flow .....	61
Figure 5-23	Formed Discrete Capacitor Element .....	33	Figure 7-19	B3 Base-Core Example with Placed Passive and Active Components on Both Sides .....	62
Figure 5-24	Printed Capacitor Element with Printed Ag Electrode .....	34	Figure 7-20	B3 Process Flow .....	62
Figure 5-25	Etched Copper Spiral Inductor Pattern .....	35	Figure 7-21	C1 Base-Core Example with Formed Passive Components in the Mounting Base and Placed Passive Components on One Side .....	64
Figure 5-26	Spiral Inductor Planning Guide .....	35	Figure 7-22	C1 Process flow .....	64
Figure 5-27	Spiral Inductor Shape Variations .....	36	Figure 7-23	C2 Base-Core Example with Formed Passive Components in the Mounting Base and Placed Active Components on One Side .....	65
Figure 5-28	Software Tools Can Improve Inductor Design .....	36	Figure 7-24	C2 Process Flow .....	65
Figure 5-29	Die attachment fluids like silver epoxy can be deposited by either standard needle dispensing or by jetting, depending on the application .....	37	Figure 7-25	C3 Base-Core Example with Formed Passive Components in the Mounting Base and Placed Passive and Active Components on One Side .....	66
Figure 5-30	Comparing Attachment Methods for “Placed” Embedded Passive Devices .....	39	Figure 7-26	C3 Process Flow .....	66
Figure 6-1	Printed “Active” Components on Dielectric .....	40	Figure 7-27	D1 Base-Core Example with Formed Passive Components in the Mounting Base and Placed Passive Components on Both Sides .....	68
Figure 6-2	Miniature Resistor Outline Dimensions .....	40	Figure 7-28	D1 Process Flow .....	68
Figure 6-3	Ceramic Based Resistor Element .....	41	Figure 7-29	D2 Base-Core Example with Formed Passive Components in the Mounting Base and Placed Active Components on Both Sides .....	69
Figure 6-4	Semiconductor Die Element .....	41	Figure 7-30	D2 Process Flow – Placed Active Components on Both Sides .....	69
Figure 6-5	Common Termination Variation for Face-Up Semiconductor Interface .....	42	Figure 7-31	D3 Base-Core Example with Formed Passive Components in the Mounting Base and Placed Passive and Active Components on Both Sides .....	70
Figure 6-6	Gold-to-Gold Interface (GGI) for Embedded Semiconductor Mounting .....	42	Figure 7-32	D3 Process Flow .....	70
Figure 6-7	Face-up Mounted Semiconductor with Solid Copper Plated Microvia Interface .....	43			
Figure 6-8	Formed Spiral Inductor Pattern .....	44			
Figure 6-9	Formed Discrete Capacitor .....	44			
Figure 7-1	Pattern Printed Discrete Capacitor Element Process Flow .....	46			
Figure 7-2	Embedded Component Printed Board Assembly; 2-6-2 Construction .....	48			
Figure 7-3	Microvia Terminated Passive Component .....	51			
Figure 7-4	Placed Passive Component with Microvia Termination Directly to Components Cu Plated Terminals .....	51			
Figure 7-5	Formed Resistor and Capacitors in the Embedded Component Base-Core .....	51			
Figure 7-6	Examples of Mounting Base Construction for an Embedded Component Base-Core .....	52			



Table 7-3	FR-4 Material Properties to Meet Assembly Exposures .....	47
Table 7-4	Examples of Non-FR-4 Material Properties to Meet Assembly Exposure .....	49
Table 7-5	Requirement Identification for Resin-Coated Copper .....	50
Table 7-6	Embedded Component Base-Core Descriptions .....	56
Table 7-7	F1 and F2 Embedded Component Base-Core Descriptions .....	74
Table 8-1	General Rules for Decision Making .....	83
Table 8-2	Embedded Design Outsourcing Model Types .....	84
Table 8-3	Prepreg Material Style and Thickness Guide (Dimensions are shown in 1/1000 inches) .....	89
Table 8-4	Key Design Measures for Suppressing EMI/RFI (Data source: Nexlogic Technologies) .....	91
Table 8-5	Solder Alloy Composition Selection .....	93
Table 8-6	Comparing Attachment Material Attributes .....	93
Table 8-7	Comparing Adhesive Material Attributes Data source: AI Technology .....	95
Table 8-8	Copper Weight and Thickness .....	97
Table 8-9	External Layer Current Carrying Capacity Rating .....	97
Table 8-10	Internal Layer Current Carrying Capacity Rating .....	98
Table 8-11	File Segmentation and Functional Requirements .....	106
Table 9-1	Product Categories .....	110
Table 9-2	Process Qualification Recommendation .....	111
Table 9-3	Embedded Base-Core Repair and Modification Recommendations .....	111
Table 10-1	Accelerated Testing for End Use Environments .....	116
Table 10-2	Temperature Cycling Requirements Mandated and Preferred Test Parameters within Mandated Conditions .....	117

# Design and Assembly Process Implementation for Embedded Components

## 1 SCOPE

This document describes the design and assembly challenges for implementing passive and active components, in either formed or placed methodology, into a printed board. The completed structure including internal electronic components is ready for surface mount and/or through-hole component attachment. The multilayered structure becomes a complete product ready for further processing in an assembly process and can be made from organic, inorganic (ceramic) or both types of material.

**1.1 Purpose** The target audiences for this document are managers, design and process engineers, and technicians who develop electronic assemblies that include an embedded component printed board as a part of the product. The purpose is to provide useful and practical information to those who are involved in the decision making of either formed or placed, passive or active components and to help establish inspection techniques, testing processes, and reliability validations.

**1.2 Intent** This document, although not a complete recipe, identifies many of the characteristics that influence the successful implementation of a robust embedded component process. In many applications, the variation between forming and placing methods and materials are reviewed with the intent to highlight significant differences that relate to the decision as to when, why, or how to establish the quality and reliability of the final product. The information also establishes the robustness that the embedded portion of the product can survive the continued processing in order to complete an Embedded Component Printed Board Assembly.

An additional challenge in implementing the processes, along with all the varieties of electronic components, internal and external, is the need to meet the legislative directives that declare certain materials as hazardous to the environment. The requirements to eliminate these materials from electronic assemblies have caused component manufacturers to rethink the materials used for encapsulation, the plating finishes on the components and the metal alloys used in the assembly attachment process.

## 2 APPLICABLE DOCUMENTS

### 2.1 IPC<sup>1</sup>

**IPC-J-STD-001** Requirements for Soldered Electrical and Electronic Assemblies

**IPC-T-50** Terms and Definitions for Interconnecting and Packaging Electronic Circuits

**IPC-D-279** Design Guidelines for Through-Hole Surface Mount Technology Printed Board Assemblies

**IPC-D-356** Bare Substrate Electrical Test Data Format

**IPC-TM-650** Test Methods Manual

**IPC-QL-653** Certification of Facilities that Inspect/Test Printed Boards, Components and Materials

**IPC-SM-784** Guidelines for Chip-on-Board Technology Implementation

**IPC-SM-785** Guidelines for Accelerated Reliability Testing of Surface Mount Attachments

**IPC-2116** Design Guide for Embedded Passive Device Printed Boards

**IPC-2181** Generic Requirements for Printed Board Assembly Products Manufacturing Description Data and Transfer Methodology

**IPC-4101** Specification for Base Materials for Rigid and Multilayer Printed Boards

**IPC-4562** Metal Foil for Printed Wiring Applications

1. [www.ipc.org](http://www.ipc.org)